

SX1278/SX1276 Wireless Module

E19 Series

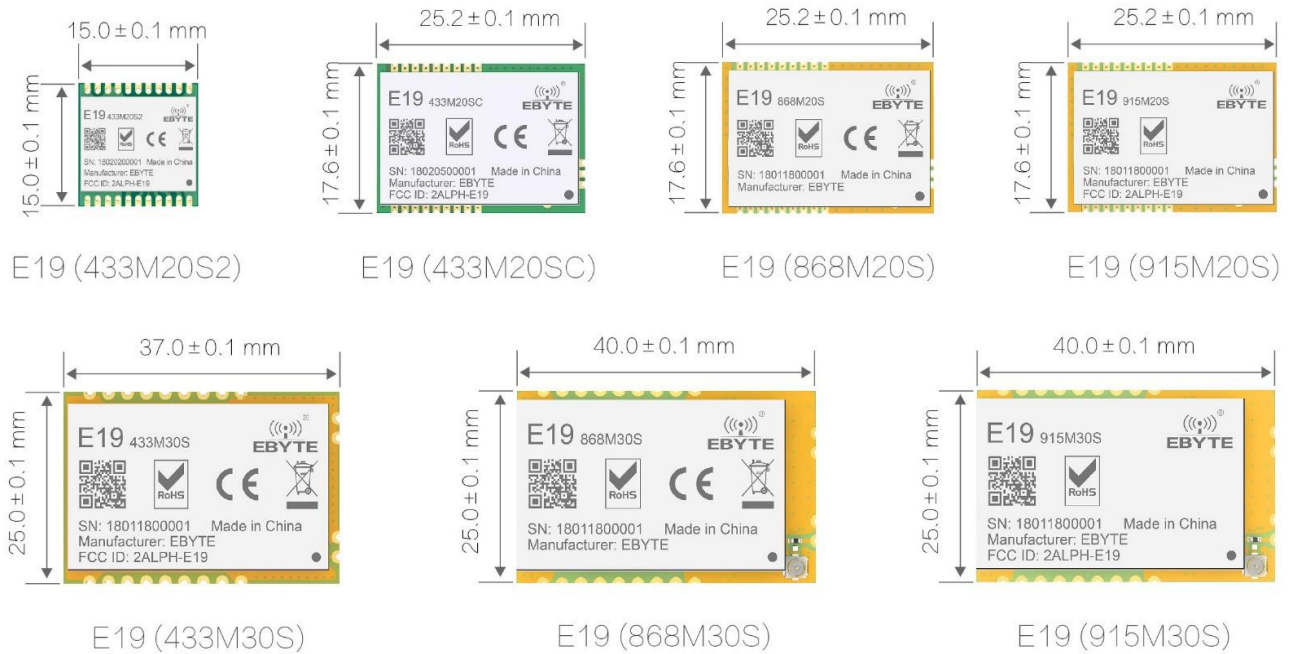
User Manual

This manual may change with the continuous improvement of the product. Please refer to the latest version of the instruction.

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Version	Revision date	Revision notes	Reviser
1.00	2017/11/2	First version	huaa
1.10	2018/2/2	Add E19 (433M20S2)	huaa

General introduction



E19 series module is a small-sized Sub 1GHz LoRa™ SMD wireless module designed by Chengdu Ebyte, based on the original imported RF chip SX1278/SX1276 from SEMTECH, supporting LoRa Spread spectrum technology, which brings longer transmission distance and has the advantages of concentrated power density and strong anti-interference.

The 30dBm module with PA(power amplifier) and low-noise amplifier enhanced the communication stability and communication distance; The 20dBm module integrated the industrial crystal oscillator, accuracy is less than 10ppm, with stable batch production, and widely used for utilities, IOT transformation and smart home.

The related RF parameters can get through the domestic and overseas certification, such as FCC, CE, RoHs etc., satisfying export demand. E19 series are hardware platforms. Without any program, users need to conduct the secondary development.

Product	Antenna type	Packing	Power	Distance
E19 (433M20SC)	Stamp hole	SMD	20dBm	5000m
E19 (433M20S2)	Stamp hole	SMD	20dBm	5000m
E19 (433M30S)	Stamp hole	SMD	30dBm	10000m
E19 (868M20S)	Stamp hole	SMD	20dBm	5000m
E19 (868M30S)	Stamp hole / IPEX	SMD	30dBm	10000m
E19 (915M20S)	Stamp hole	SMD	20dBm	5000m
E19 (915M30S)	Stamp hole / IPEX	SMD	30dBm	10000m

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1. Technical parameters

1.1 General parameters

Model No.	IC	Size	Net WT	Operating temp.	Operating humidity	Storage temp.
E19 (433M20SC)	SX1278	17.6*25.2 mm	1.6±0.1g	-40 ~ 85°C	10% ~ 90%	-40 ~ 125°C
E19 (433M20S2)	SX1278	15.0*15.0 mm	0.9±0.1g	-40 ~ 85°C	10% ~ 90%	-40 ~ 125°C
E19 (433M30S)	SX1278	25.0*37.0 mm	5.2±0.1g	-40 ~ 85°C	10% ~ 90%	-40 ~ 125°C
E19 (868M20S)	SX1276	17.6*25.2 mm	1.6±0.1g	-40 ~ 85°C	10% ~ 90%	-40 ~ 125°C
E19 (868M30S)	SX1276	25.0*40.0 mm	5.2±0.1g	-40 ~ 85°C	10% ~ 90%	-40 ~ 125°C
E19 (915M20S)	SX1276	17.6*25.2 mm	1.6±0.1g	-40 ~ 85°C	10% ~ 90%	-40 ~ 125°C
E19 (915M30S)	SX1276	25.0*40.0 mm	5.2±0.1g	-40 ~ 85°C	10% ~ 90%	-40 ~ 125°C

1.2 Electrical parameters

1.2.1 Transmitting current

Model No.	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	100	110	120	mA	<ul style="list-style-type: none"> When designing current supply circuit, 30% margin is recommended to be remained so as to ensure long-term stable operation of the whole module; The current at the instant of transmitting may be high, but the total energy consumed may be lower due to very short transmitting time; When using external antenna, the impedance matching degree at different frequency points between antenna and module may affect the transmitting current value at different levels.
E19 (433M20S2)	110	120	130	mA	
E19 (433M30S)	570	630	690	mA	
E19 (868M20S)	570	630	690	mA	
E19 (868M30S)	570	620	682	mA	
E19 (915M20S)	100	110	120	mA	
E19 (915M30S)	570	630	690	mA	

1.2.2 Receiving current

Model No.	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	13	14	15	mA	<ul style="list-style-type: none"> The current consumed when the RF chip is only working at receiving mode is called as receiving current , the tested receiving current may be higher for some RF chips with communication protocol or the developers have loaded their own protocol to the whole module. The current at pure receiving mode will be mA level, the users have to realize μA level receiving current through firmware development.
E19 (433M20S2)	13	14	15	mA	
E19 (433M30S)	18	20	22	mA	
E19 (868M20S)	13	14	15	mA	
E19 (868M30S)	21	23	25	mA	
E19 (915M20S)	13	14	15	mA	
E19 (915M30S)	21	23	25	mA	

1.2.3 Turn-off current

Model No.	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	0.5	1.0	2.5	μA	<ul style="list-style-type: none"> ● The turn-off current means the current consumed when CPU, RAM, Clock and some registers remain operating while SoC is at very low power consumption status. ● The turn-off current is always lower than the current consumed when the power supply source of the whole module is at no-load status.
E19 (433M20S2)	0.5	1.0	2.5	μA	
E19 (433M30S)	1.5	3.0	4.5	μA	
E19 (868M20S)	0.5	1.0	2.5	μA	
E19 (868M30S)	1.5	3.0	4.5	μA	
E19 (915M20S)	0.5	1.0	2.5	μA	
E19 (915M30S)	1.5	3.0	4.5	μA	

1.2.4 Supply voltage

Model No.	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	1.8	3.3	3.6	V DC	<ul style="list-style-type: none"> ● If the voltage is at maximum value for long time, the module may be damaged; ● The power supply pin has certain surge-resistance ability, but the potential pulse higher than the maximum power supply voltage; ● The power supply voltage is recommended to be higher than 3.0V, if the voltage is lower than 3.0V, the RF parameters will be affected at different degrees.
E19 (433M20S2)	1.8	3.3	3.6	V DC	
E19 (433M30S)	3.3	5.0	5.5	V DC	
E19 (868M20S)	1.8	3.3	3.6	V DC	
E19 (868M30S)	3.3	5.0	5.5	V DC	
E19 (915M20S)	1.8	3.3	3.6	V DC	
E19 (915M30S)	3.3	5.0	5.5	V DC	

1.2.5 Communication level

Model No.	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	1.8	3.3	3.6	V DC	<ul style="list-style-type: none"> ● If the communication level is higher than the allowed maximum value, the module may be damaged; ● Although the communication level can be switched with various methods, the power consumption of the whole module will be affected at great degree.
E19 (433M20S2)	1.8	3.3	3.6	V DC	
E19 (433M30S)	3.3	5.0	5.5	V DC	
E19 (868M20S)	1.8	3.3	3.6	V DC	
E19 (868M30S)	3.3	5.0	5.5	V DC	
E19 (915M20S)	1.8	3.3	3.6	V DC	
E19 (915M30S)	3.3	5.0	5.5	V DC	

1.3 RF parameters

1.3.1 Transmitting Power

Model No.	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	19	20	20.5	dBm	<ul style="list-style-type: none"> ● Due to the error of the materials, each LRC component has $\pm 0.1\%$ error, so error accumulation will occur since multiple LRC components are used in the whole RF circuit, and the transmitting currents will be different; ● The power consumption can be lowered by lowering the transmitting power, but the efficiency of the internal PA will be decreased by lowering transmitting power due to various reasons; ● The transmitting power will be lowered by lowering the power supply voltage.
E19 (433M20S2)	19	20	20.7	dBm	
E19 (433M30S)	28.5	30	30	dBm	
E19 (868M20S)	19	20	20.4	dBm	
E19 (868M30S)	28.5	30	30	dBm	
E19 (915M20S)	19	20	20.6	dBm	
E19 (915M30S)	28.5	30	30	dBm	

1.3.2 Receiving sensitivity

Model No.	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	-145	-147	-148	dBm	<ul style="list-style-type: none"> The current sensitivity is tested under the Coding rate of 4/5 and spread spectrum factor of 12 Due to the error of the materials, each LRC component has $\pm 0.1\%$ error, so error accumulation will occur since multiple LRC components are used in the whole RF circuit, and the transmitting currents will be different at different modules; The receiving sensitivity will be reduced and range will be shortened while increasing the air data rate.
E19 (433M20S2)	-145	-147	-148	dBm	
E19 (433M30S)	-146	-148	-150	dBm	
E19 (868M20S)	-145	-147	-148	dBm	
E19 (868M30S)	-146	-148	-150	dBm	
E19 (915M20S)	-145	-147	-148	dBm	
E19 (915M30S)	-146	-148	-150	dBm	

1.3.3 Recommended Frequency

Model No	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	410.0	433.0	441.0	MHz	<ul style="list-style-type: none"> It ensures that the performance of the module can reach the standard if it works in recommended operating frequency. It is recommended to avoid the crowded frequencies, such as 433.0MHz, 868.0MHz, 915MHz and other integer frequencies.
E19 (433M20S2)	410.0	433.0	441.0	MHz	
E19 (433M30S)	410.0	433.0	441.0	MHz	
E19 (868M20S)	862.0	868.0	893.0	MHz	
E19 (868M30S)	862.0	868.0	893.0	MHz	
E19 (915M20S)	900.0	915.0	931.0	MHz	
E19 (915M30S)	900.0	915.0	931.0	MHz	

1.4 Tested parameters

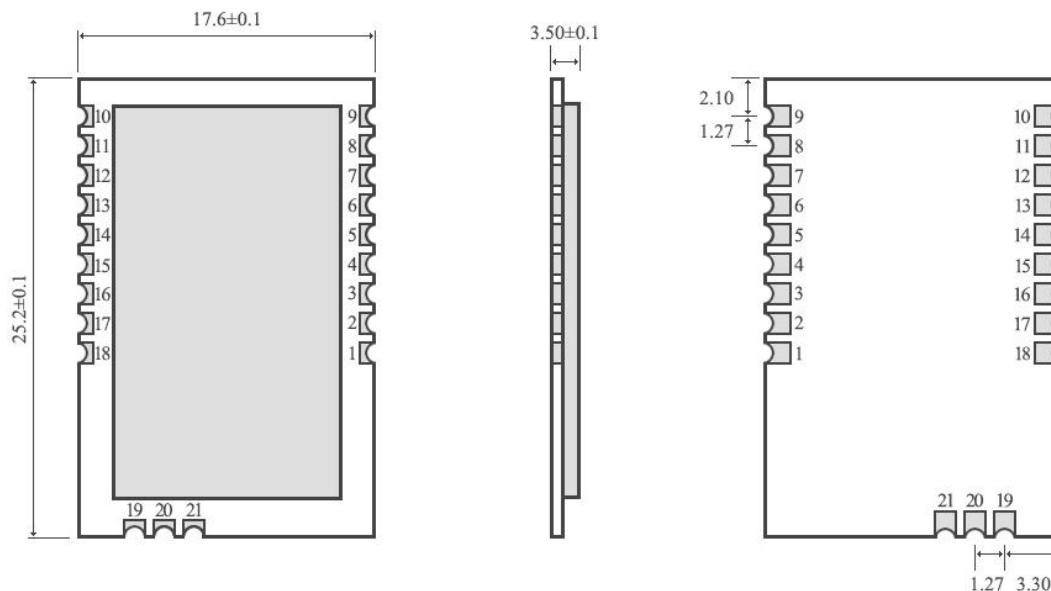
1.4.1 Tested distance

Model No	Min	Typ	Max	Unit	Remark
E19 (433M20SC)	4500	5000	5500	m	<ul style="list-style-type: none"> The external antenna used is of 5dBi gain and vertical polarization; The interval between each data packet is 2s, sending 100 packets with 30 bytes in each packet, the range at data lose rate of lower than 5% is valid range; In order to obtain meaningful and reproduceable results, we conducted the tests under in clear weather with little electromagnetic interference at suburb areas ; Distance may be shorter with interference or obstacles.
E19 (433M20S2)	4500	5000	5500	m	
E19 (433M30S)	9000	10000	11000	m	
E19 (868M20S)	4500	5000	5500	m	
E19 (868M30S)	9000	10000	11000	m	
E19 (915M20S)	4500	5000	5500	m	
E19 (915M30S)	9000	10000	11000	m	

2. Mechanical properties

2.1. E19 (433M20SC)/ E19 (868M20S)/ E19 (915M20S)

2.1.1 Dimensions

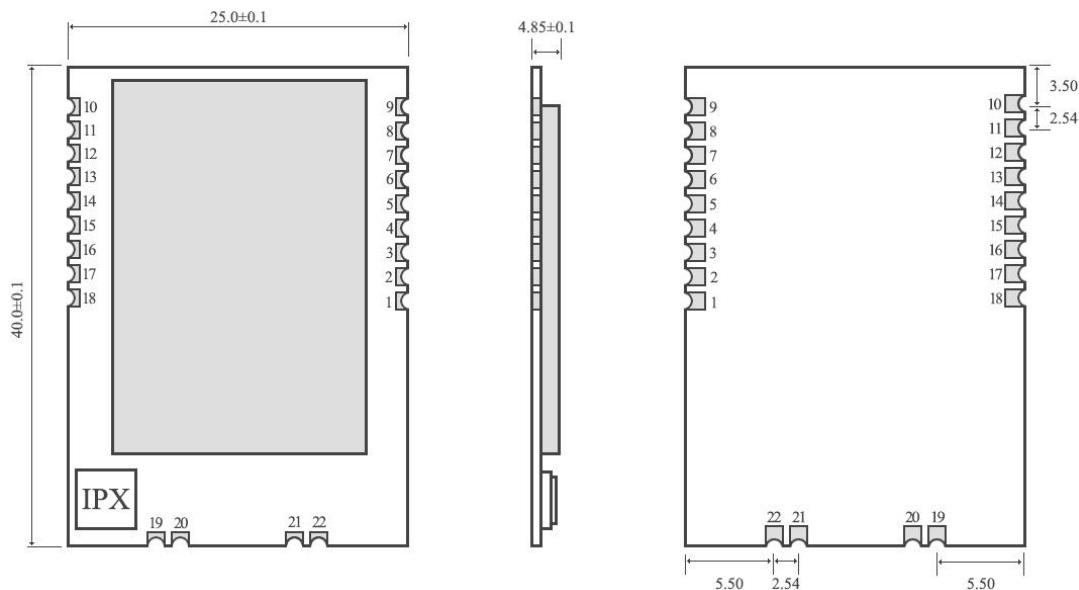


2.1.2 Pin definition

Pin No.	Name	Direction	Usage
1	GND	Input	Ground electrode, connected to the power reference ground.
2	DIO5	Input /Output	Configurable IO interface(See more details in SX1278 data sheet
3	DIO4	Input /Output	Configurable IO interface(See more details in SX1278 data sheet
4	DIO3	Input /Output	Configurable IO interface(See more details in SX1278 data sheet
5	DIO2	Input /Output	Configurable IO interface(See more details in SX1278 data sheet
6	DIO1	Input /Output	Configurable IO interface(See more details in SX1278 data sheet
7	DIO0	Input /Output	Configurable IO interface(See more details in SX1278 data sheet
8	RST	Input	Reset
9	NC	--	Not connect
10	GND	Input	Ground electrode, connected to the power reference ground.
11	VCC	Input	Power supply 1.8V-3.6V DC. 3.3V and external ceramic filter capacitor are recommended.)
12	SCK	Input	SPI clock
13	MISO	Output	Master input slave output
14	MOSI	Input	Master output slave input
15	NSS	Input	Chip select
16	TXEN	Input	Radio frequency switch control, make sure the TXEN pin is in high level, RXEN pin is in low level when transmitting.
17	RXEN	Input	Radio frequency switch control, Make sure the RXEN pin is in high level ,TXEN pin is in low level when receiving.
18	GND		Ground electrode, connected to the power reference ground.
19	GND		Ground electrode, connected to the power reference ground.
20	ANT	Output	Antenna
21	GND		Ground electrode, connected to the power reference ground.

2.2. E19 (433M30S)/ E19 (868M30S)/ E19 (915M30S)

2.2.1 Dimensions

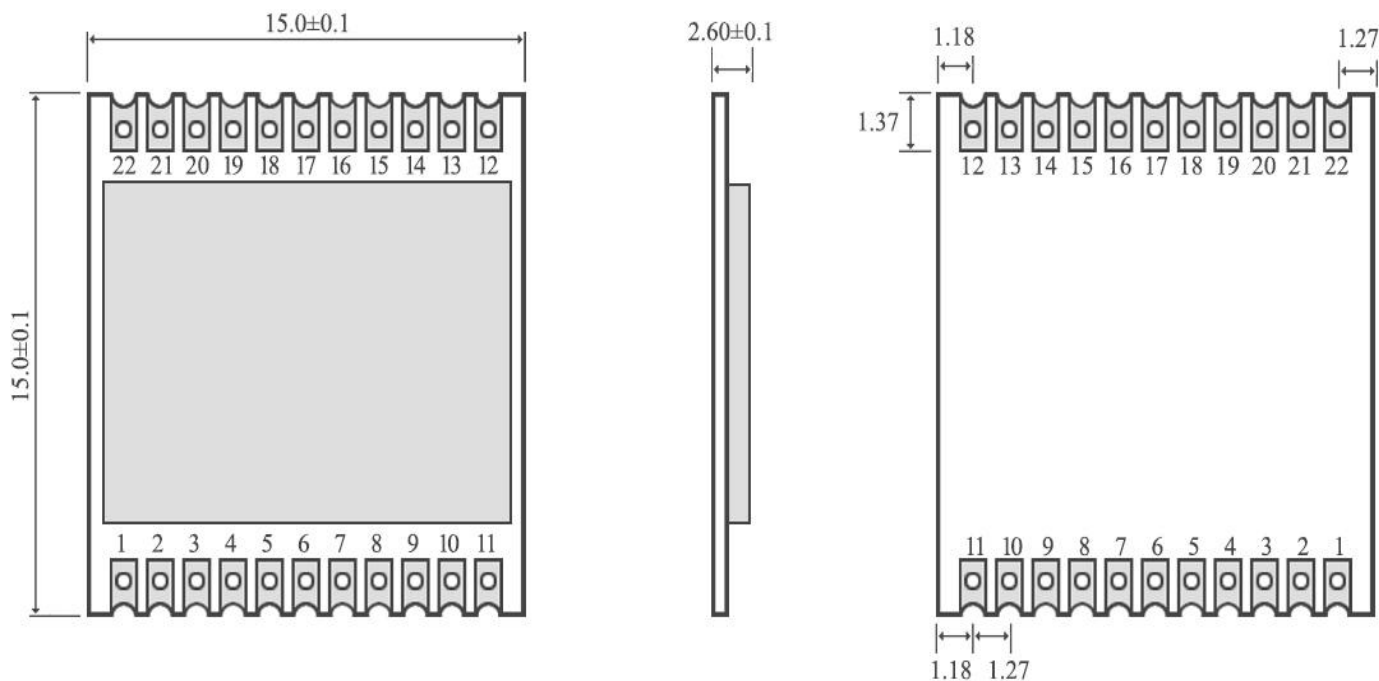


2.2.2 Pin definition

Pin No.	Name	Direction	Usage
1	GND		Ground electrode, connected to the power reference ground.
2	DIO5	Input/Output	Configurable IO port (Please find more on SX1276 datasheet) .
3	DIO4	Input/Output	Configurable IO port (Please find more on SX1276 datasheet)
4	DIO3	Input/Output	Configurable IO port (Please find more on SX1276 datasheet)
5	DIO2	Input/Output	Configurable IO port (Please find more on SX1276 datasheet)
6	DIO1	Input/Output	Configurable IO port (Please find more on SX1276 datasheet)
7	DIO0	Input/Output	Configurable IO port (Please find more on SX1276 datasheet)
8	RST	Input	Reset
9	NC		Not connect
10	GND		Configurable IO port (Please find more on SX1276 datasheet)
11	VCC		Power supply: 4.75~5.5V (Ceramic filter capacitor is advised to add)
12	SCK	Input	SPI clock
13	MISO	Output	Master output slave input
14	MOSI	Input	Master input slave output
15	NSS	Input	Chip select
16	TXEN	Input	Radio frequency switch control, make sure the TXEN pin is in high level, RXEN pin is in low level when transmitting.
17	RXEN	Input	Radio frequency switch control, Make sure the RXEN pin is in high level ,TXEN pin is in low level when receiving.
18	GND		Ground electrode, connected to the power reference ground
19	ANT		Antenna
20	GND		Ground electrode, connected to the power reference ground
21	GND		Ground electrode, connected to the power reference ground
22	GND		Ground electrode, connected to the power reference ground
★ Please find more on SX127X6 datasheet from SEMTECH ★			

2.3. E19 (433M20S2)

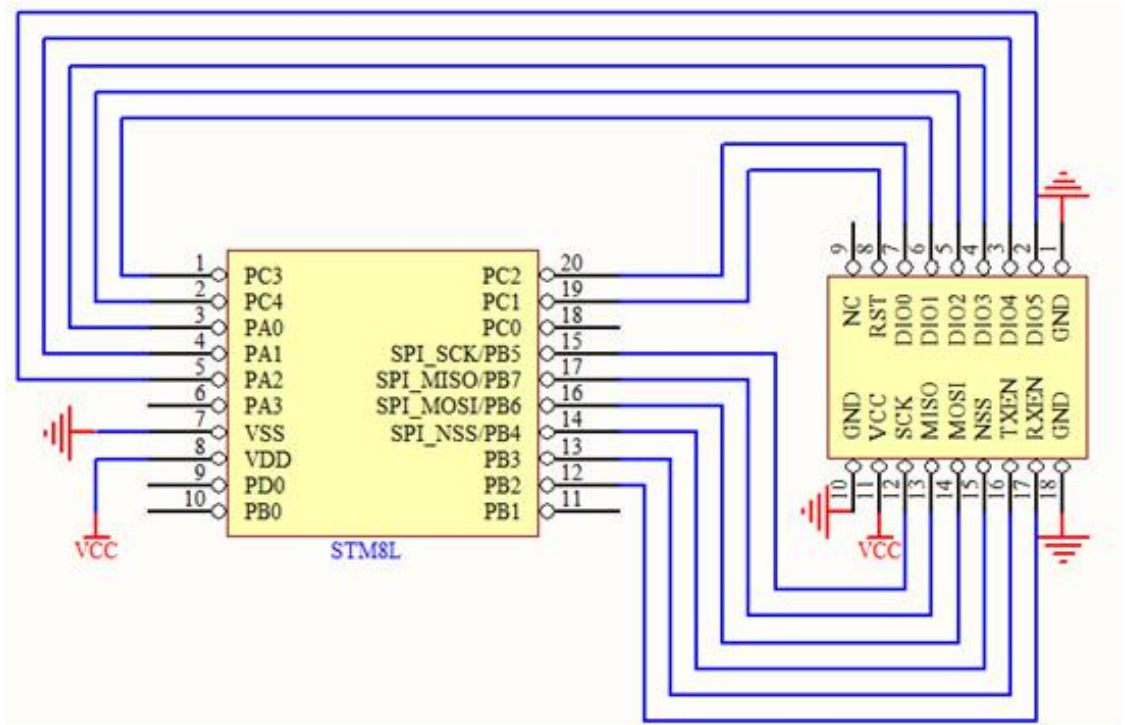
2.3.1 Dimensions



2.3.2 Pin definition

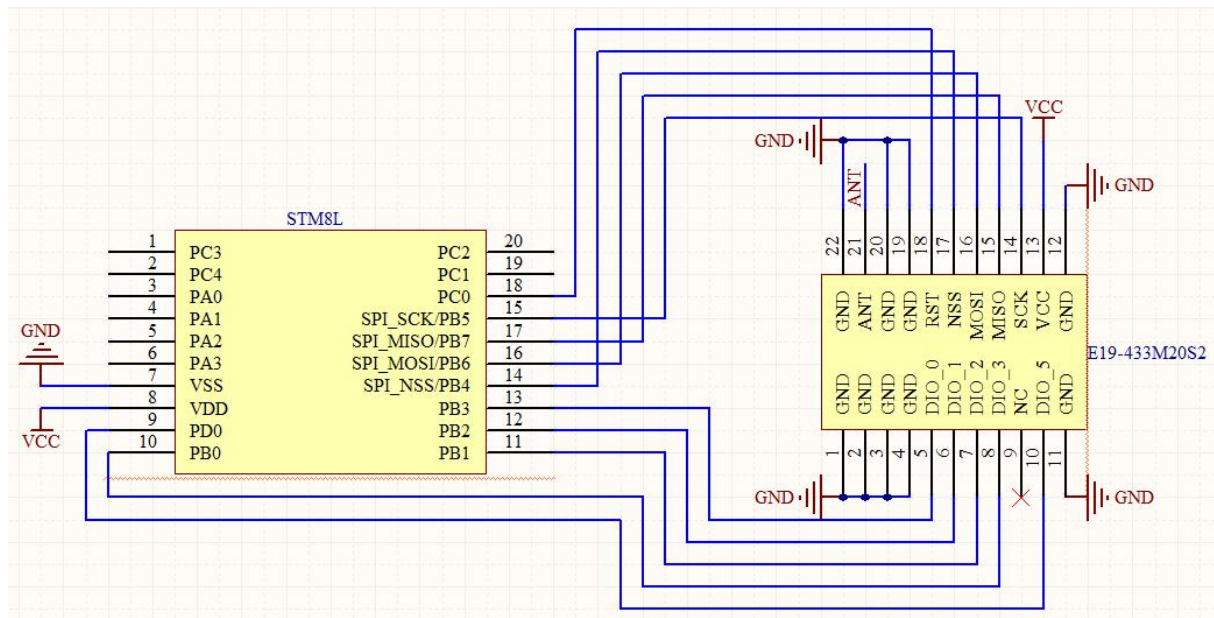
Pin No.	Name	Direction	Usage	Pin No.
1、2、3、4、11、12、19、20、22	GND	GND		Ground electrode, connected to the power reference ground.
5	DIO0	DIO0	Input/Output	Configurable IO port (Please find more on SX1278 datasheet)
6	DIO1	DIO1	Input/Output	Configurable IO port (Please find more on SX1278 datasheet)
7	DIO2	DIO2	Input/Output	Configurable IO port (Please find more on SX1278 datasheet)
8	DIO3	DIO3	Input/Output	Configurable IO port (Please find more on SX1278 datasheet)
9	NC	DIO4		Not connect
10	DIO5	DIO5	Input/Output	Configurable IO port (Please find more on SX1278 datasheet)
13	VCC	VBAT1, VBAT2, VBAT3		Power supply: 1.8~3.6V (recommended 3.3V, Ceramic filter capacitor is advised to add)
14	SCK	SCK	Input	SPI clock input
15	MISO	MISO	Output	SPI clock input
16	MOSI	MOSI	Input	SPI clock input
17	NSS	NSS	Input	Chip select, start SPI communication, low level enable
18	RST	NRESET	Input	Reset, low level enable
21	ANT	-		Antenna
★ Please find more on SX1278 datasheet from SEMTECH ★				

3.Recommended circuit diagram



Brief introduction of connection between module and MCU (STM8L)

3.1. E19 (433M20S2)



4. Remark

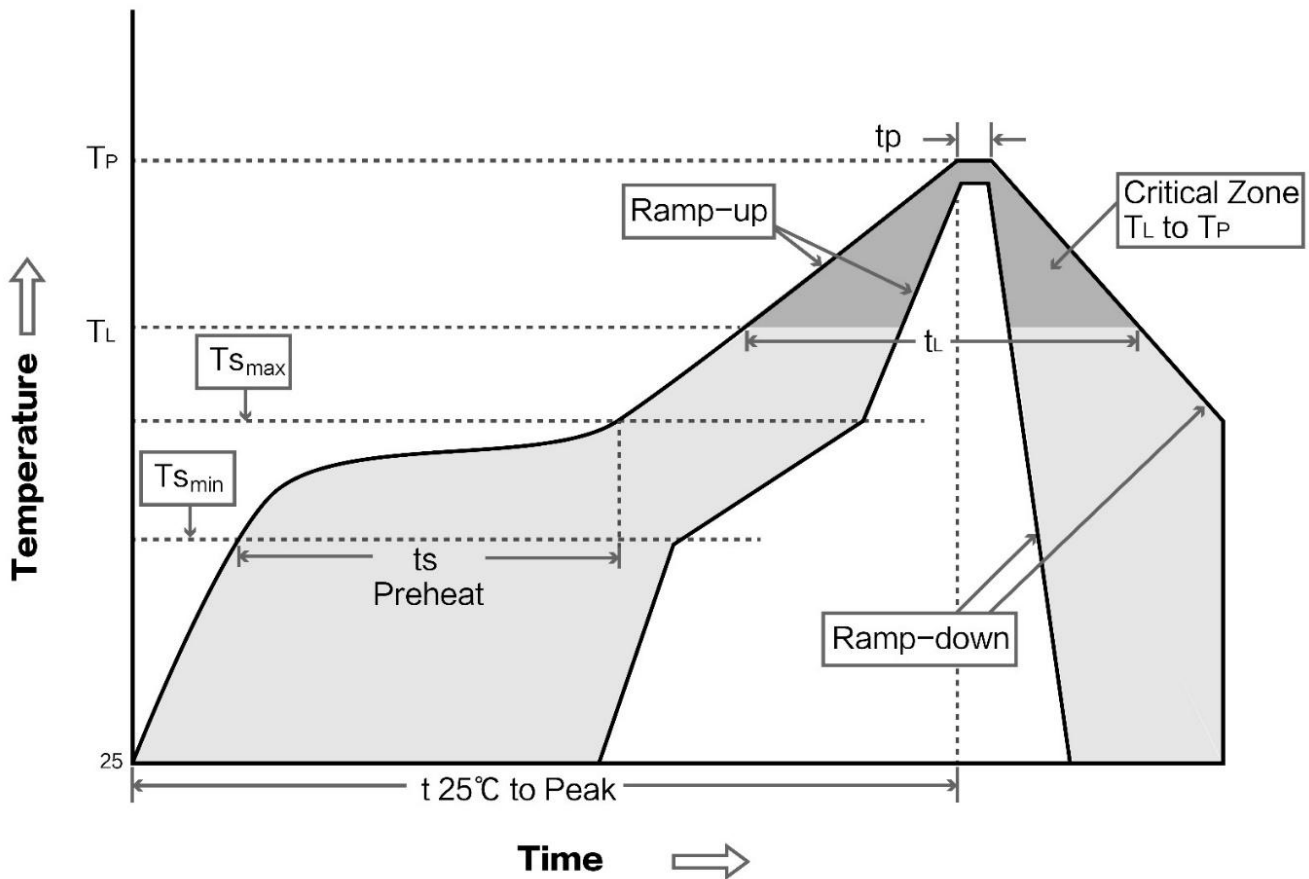
- DIO0, DIO1, DIO2, DIO3, DIO4, DIO5 is generally purpose I/O, can be configured into multiple function, please check SX1278/SX1276 manual for more details, floating is allowed.
- RST, TXEN, RXEN pin must be connected, in which RST control the reset of chip, TXEN, RXEN pin control RF switch.
- Make sure the grounding is good, with low power ripple, also should increase filter capacitor and as close as possible to the VCC and GND pins.
- SPI communication rate should not be set too high, usually around 1M.
- Make sure TXEN pin is high level, RXEN pin is low level when transmitting.
make sure RXEN pin is high level, TXEN pin is low level when receiving.
make sure TXEN, RXEN pin is low level before turning off.
- The register configuration can be reinitialized to obtain higher stability when the chip is invalid.

5. Production Guidance

5.1 Reflow Temperature

Profile Feature	Sn-Pb Assembly	Pb-Free Assembly
Solder Paste	Sn63/Pb37	Sn96.5/Ag3/Cu0.5
Preheat Temperature min (T _{smin})	100°C	150°C
Preheat temperature max (T _{smax})	150°C	200°C
Preheat Time (T _{smin} to T _{smax})(t _s)	60-120 sec	60-120 sec
Average ramp-up rate(T _{smax} to T _p)	3°C/second max	3°C/second max
Liquidous Temperature (TL)	183°C	217°C
Time (t _L) Maintained Above (TL)	60-90 sec	30-90 sec
Peak temperature (T _p)	220-235°C	230-250°C
Average ramp-down rate (T _p to T _{smax})	6°C/second max	6°C/second max
Time 25°C to peak temperature	6 minutes max	8 minutes max

5.2 Reflow Graph



6. FAQ

6.1 The communication distance is too close

- When there' s straight Communication barrier, the communication distance will be reduced accordingly.
- Temperature, humidity and same frequency interference will increase the rate of communication packet loss.
- Ground absorption, reflected radio waves, and closing to ground will lead to poor test result.
- Sea water has a strong ability to absorb radio waves, so test near the sea is not recommended .
- If antennas surrounded by metal items or placed in metal shell, the signal will be weakened badly.
- Power register is set wrongly or air data rate too high.(The higher the air data rate, the closer the distance.
- In room temperature, the power voltage will be less than 2.5V. The lower the the power voltage, the smaller the power.
- The antenna is unmatched to the module or the quality of antenna.

6.2 The module can be damaged easily

- Please check the power supply, which should be 1.8v-3.8v. If the value exceeds that, the module will be damaged.
- Please check the stability of power supply. The voltage cannot be in fluctuations frequently.
- Please ensure all the installation operations are anti-static.
- Please ensure the humidity in the procedure of installation and operation should not be too high because some electrical parts are humidity sensitive device.
- Please do not use it in a too high or too low temperature environment if there' s no special requirement.

7. Important statement

- Ebyte reserves the rights of final interpretation and revision for all the involved contents in this manual.
- With the continuous improvement of hardware and software, this manual may subject to change without notice. Please refer to the latest version.
- Users can follow the product news on our official website so as to gain the latest information.

8. About us

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